

P-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)		
- 200	2.35 at V _{GS} = - 10 V	- 0.49	8.0		
	2.45 at V _{GS} = - 6.0 V	- 0.48	6.0		

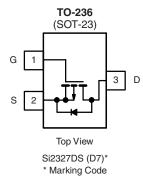
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- Ultra Low On-Resistance
- Small Size



APPLICATIONS

• Active Clamp Circuits in DC/DC Power Supplies



Ordering Information: Si2327DS -T1-E3 (Lead (Pb)-free)

Si2327DS -T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	5 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	- 200		V
Gate-Source Voltage		V_{GS}	± 20		
O	T _A = 25 °C	I _D	- 0.49	- 0.38	
Continuous Drain Current (T _J = 150 °C) ^{a, b}	T _A = 70 °C		- 0.39	- 0.31	
Pulsed Drain Current		I _{DM}	- 1.0		Α
Continuous Source Current (Diode Conduction) ^{a, b}		I _S	- 1.0	- 0.6	
Single Pulse Avalanche Current	L = 1.0 mH	I _{AS}	4.0		
Single Pulse Avalanche Energy	L = 1.0 mn	E _{AS}	0.8		mJ
	T _A = 25 °C	P _D	1.25	0.75	W
Maximum Power Dissipation ^{a, b}	T _A = 70 °C		0.8	0.48	v v
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
	t ≤ 5 s	R _{thJA}	75	100		
Maximum Junction-to-Ambient ^a	Steady State		120	166	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	40	50		

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.

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			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 200			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 2.5		- 4.5	\ \ \	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	1	V _{DS} = - 200 V, V _{GS} = 0 V			- 1	μΑ	
	I _{DSS}	V _{DS} = - 200 V, V _{GS} = 0 V, T _J = 55 °C			- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -15 \text{ V}, V_{GS} = 10 \text{ V}$	- 1.0			Α	
	D	$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$		1.9	2.35	Ω	
Drain-Source On-Resistance ^a	R _{DS(on)}	V _{GS} = - 6.0 V, I _D = - 0.5 A		1.96	2.45		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 0.5 A		1.8		S	
Diode Forward Voltage	V_{SD}	I _S = - 1.0 A, V _{GS} = 0 V		- 0.85	- 1.2	V	
Dynamic ^b	•						
Total Gate Charge	Q_g	V 100 V V 10 V		8.0	12		
Gate-Source Charge	Q _{gs}	$V_{DS} = -100 \text{ V}, V_{GS} = 10 \text{ V}$ $I_{D} \cong -0.5 \text{ A}$		1.3		nC	
Gate-Drain Charge	Q_{gd}	1D = - 0.3 A		2.5			
Gate Resistance	R_g	f = 1.0 MHz		8.0		Ω	
Input Capacitance	C _{iss}			340	510		
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		25		pF	
Reverse Transfer Capacitance	C _{rss}			14			
Switching ^c	•						
Turn On Time	t _{d(on)}	V_{DD} = - 100 V, R_L = 100 Ω $I_D \simeq$ - 1.0 A, V_{GEN} = - 10 V		8	12	ns	
Turn-On Time	t _r			11	17		
Turn Off Time	t _{d(off)}	$R_{a} = 6 \Omega$		16	25		
Turn-Off Time	t _f	g – 5 22		11	17		
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = 0.5 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$	1	140	200	nC	

Notes:

- a. Pulse test: PW \leq 300 μs duty cycle \leq 2 %.
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

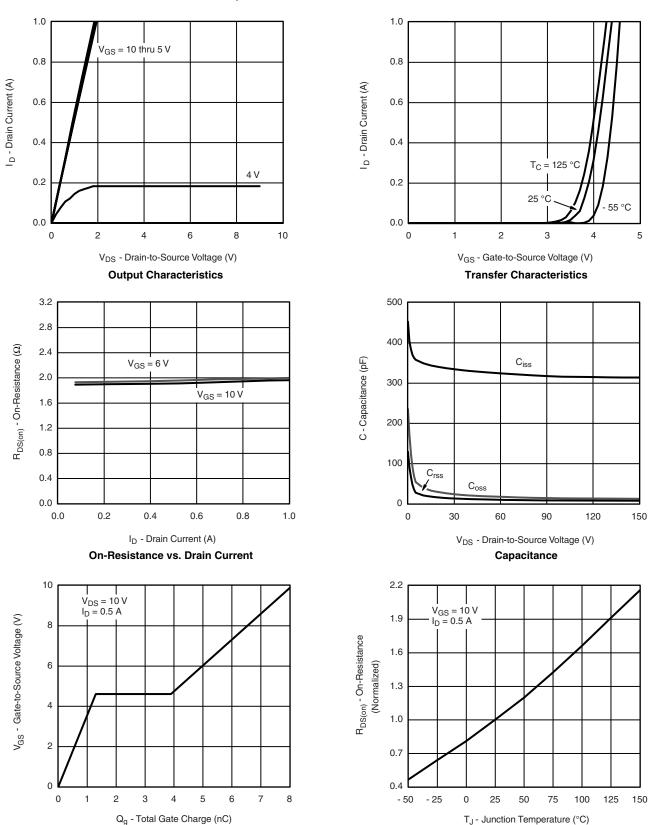
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.







TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



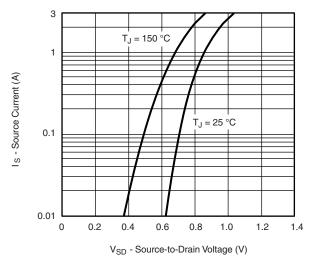
Gate Charge

T_J - Junction Temperature (°C)

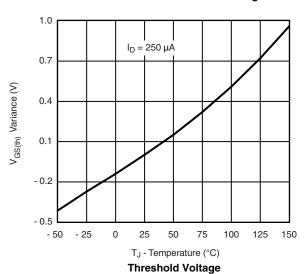
On-Resistance vs. Junction Temperature

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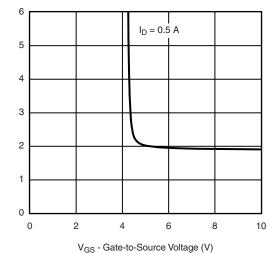
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



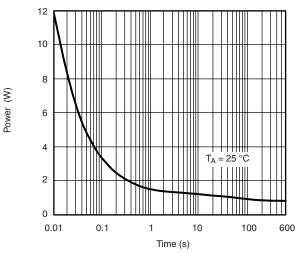
Source-Drain Diode Forward Voltage



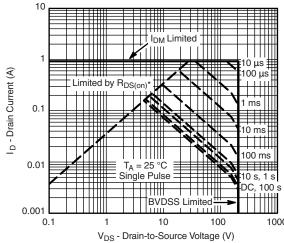
 $R_{DS(on)}$ - On-Resistance (Ω)



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power



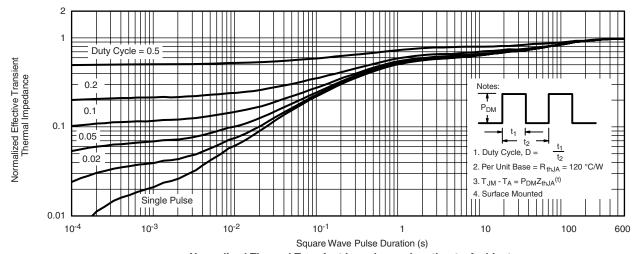
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

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